

Abstract of the Disclosure

A process of manufacturing printed circuit boards which is useful in the formation of printed circuit boards containing both areas of thick conductive traces and areas of fine resolution conductors in a single conductive layer, and printed circuit boards formed from such a process. A conductive core is first fabricated containing areas of thick conductors on a relatively thin conductive base. The conductive core is then bonded to a sublayer such as "prepreg" with the thick conductive areas adjacent to the sublayer in order to form a relatively flat laminate. Proper bonding typically requires the use of high resin "prepreg" sublayer. In the alternative, an additional inner layer of pure resin can be inserted between the conductive core and the insulating sublayer prior to bonding. After bonding, the conductive surface of the laminate is formed into printed conductor traces by methods known in the art. For example, chemical etching may be used to remove conductive material not comprising the printed circuits. In various embodiments of the invention a solder mask coating is applied to the completed printed circuit board. By use of this process, a single layer printed circuit comprising both thick conductor traces and fine resolution traces is possible. This invention is also useful in manufacturing a printed circuit core or layer suitable for use as a component in a multilayer printed circuit board where it is desirable that a relative flat layer containing thick conductor traces be provided.